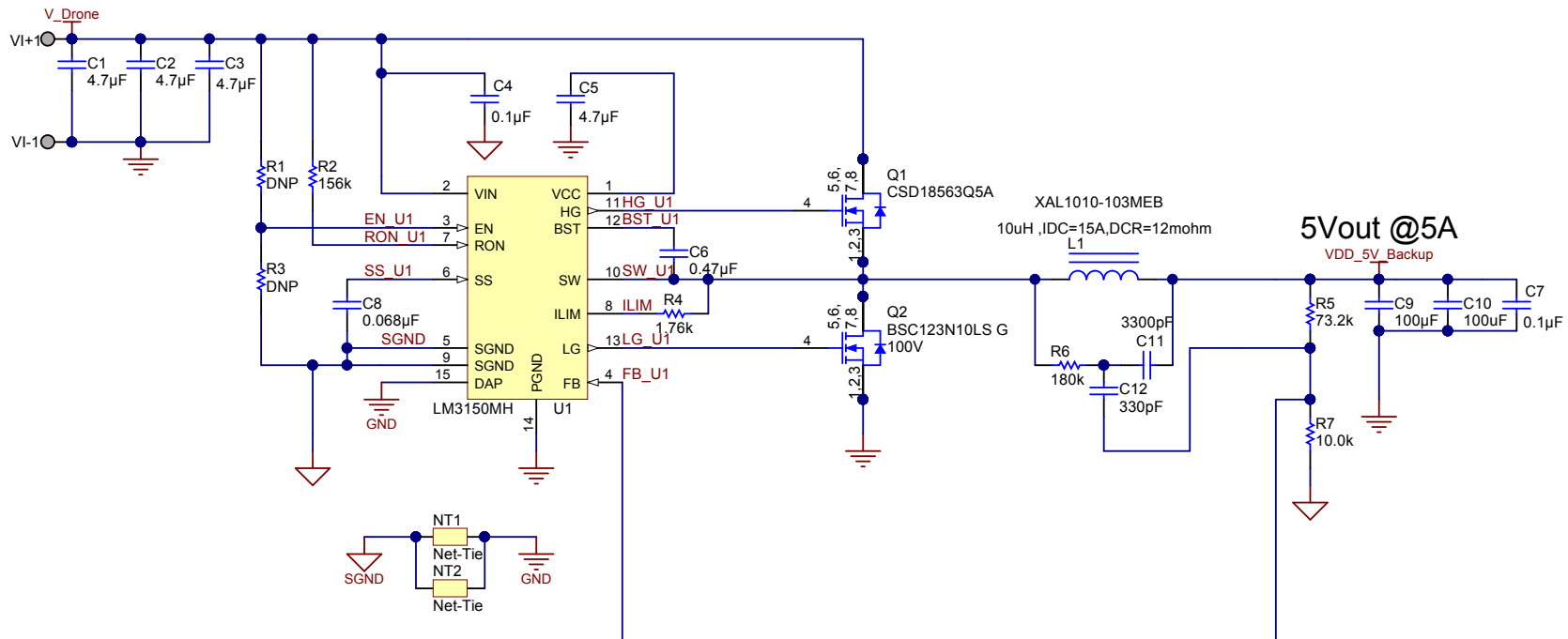
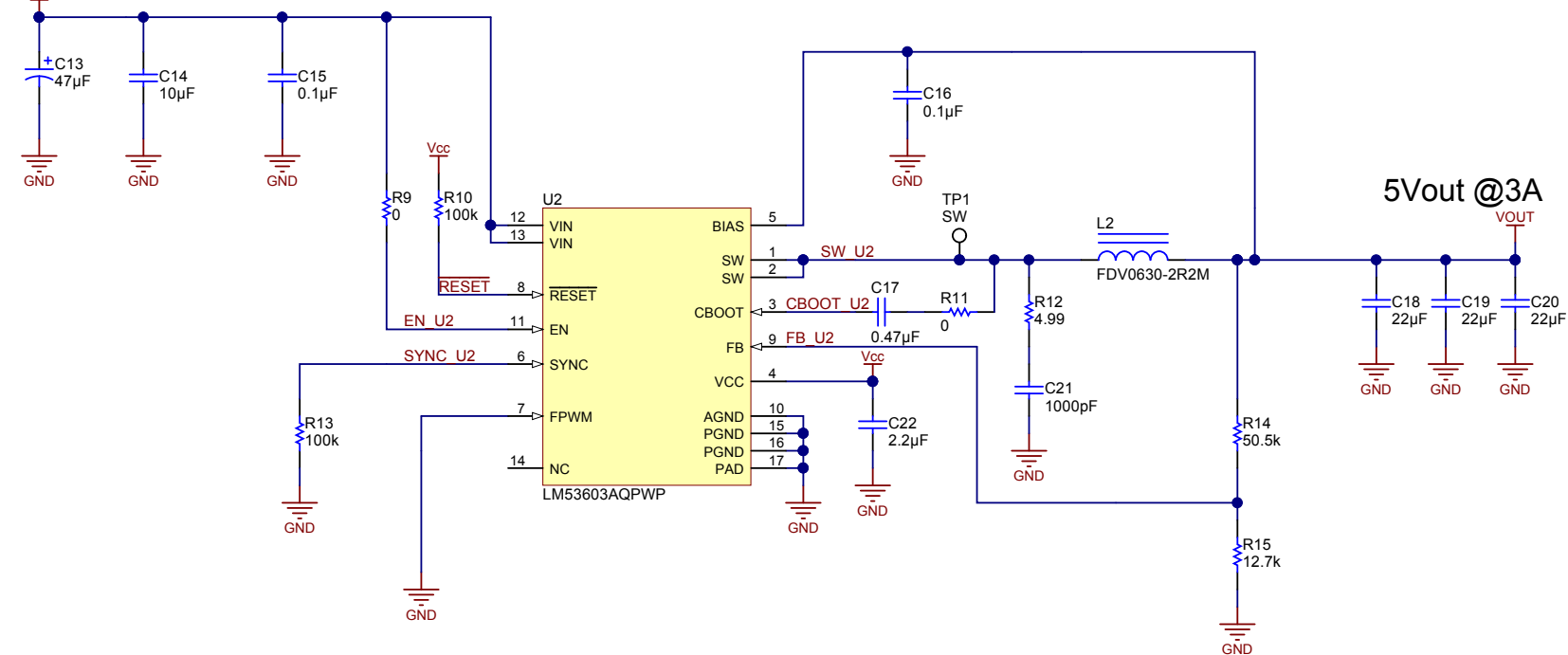


6V-40Vin



V\_Drone



Designed for: Public Release | Mod. Date: 8/7/2015

Project Title: Drone AUX SMPS

Sheet Title:

Assembly Variant: [No Variations]

File: PMP10650\_Sch REV1\_SchDoc

Contact: <http://www.ti.com/support>

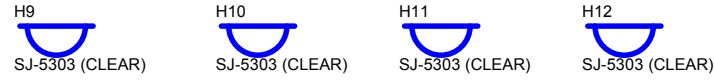
Sheet: 1 of 1

Size: B



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Number: PMP10650 | Rev: E1  
 SVN Rev: Not in version control  
 Drawn By:  
 Engineer: Ambresh Tripathi



PCB Number: PMP10650  
PCB Rev: E1

PCB LOGO  
Texas Instruments

PCB LOGO  
Pb-Free Symbol

PCB LOGO  
FCC disclaimer

You should delete the nylon screws/standoffs and/or the bumpers as needed for your design (or substitute other parts from Hardware.IntLib). Bumpers are cheaper, but provide less clearance.

Deleting anything else from this page may result in your EVM submission being rejected (until you add them back).

Update the Label Text in the Label Table as needed for each Assembly Variant.

You can delete this note too.

Label Table	
Variant	Label Text
001	ChangeMe!
002	ChangeMe!

LBL1  
PCB Label  
Size: 0.65" x 0.20 "

ZZ1  
Label Assembly Note  
This Assembly Note is for PCB labels only

ZZ2  
Assembly Note  
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3  
Assembly Note  
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4  
Assembly Note  
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

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Number: PMP10650	Rev: E1	Designed for: Public Release	Mod. Date: 4/8/2015
SVN Rev: Not in version control	Assembly Variant: [No Variations]	Sheet Title:	Sheet: 1 of 1
Drawn By:	File: Hardware_ANSI-B_SchDoc	Size: B	
Engineer: Ambresh Tripathi	Contact: <a href="http://www.ti.com/support">http://www.ti.com/support</a>		



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